

21. (Amended) A circuit board on which is mounted the electronic component as defined in claim 14.

22. (Amended) An electronic instrument equipped with the electronic component as defined in claim 14.

31. (Amended) The method of manufacture of an interconnect substrate as defined in claim 23, wherein: positioning holes are formed in the first and second substrates; and before the disposition step, a step is included in which a jig is put into the positioning holes and the first and second substrates are positioned.

38. (Amended) The method of manufacture of an electronic component as defined in claim 32, wherein the disposition step is carried out after the first mounting step.